



Product Specification

Product:	Heating Resistor Paste For Borosilicate Glass Substrates
Part Number:	05M26

Application Scope :

This product is suitable for high borosilicate glass heating circuit.

Usage Conditions :

Substrate	Borosilicate glass
Printing	200-250 mesh screen printing
Leveling	Let it level at room temperature for 5-15 minutes (adjust time based on actual leveling conditions).
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (if the baking temperature is below 300°C, the baking time may be adjusted based on actual conditions).
Firing Condition	The sintering temperature is 550~600°C (recommended value) and the sintering time is 10 minutes.
Thinner	ST1001

Characteristics :

1. Paste Characteristics :

Characteristic	Standard	Test Method And Conditions
1 Fineness	$\leq 8\mu\text{m}$	FOG test
2 Viscosity	120-280Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, operating at 10rpm and $25\pm 1^\circ\text{C}$, with adjustable viscosity according to user requirements.

2. Characteristics After Curing :

Under the 1-sintering condition, the film thickness is 8-12 μm .

Check fired film produced under the conditions specified in 1) , (Film thickness is 8-12 μm .)



Characteristics		Standard	Test Method And Conditions
3	Appearance	Compact and dense	Eyeballing
4	Resistivity	As below form	Standard film thickness: 10 μm
	Temperature Coefficient (TCR)	As below form	HTCR 25-125°C

Product Line		Heating Resistor Paste For Aluminum Substrates			
P/N		Resistivity (Ω/\square)	TCR (ppm/ $^{\circ}\text{C}$)	Sintering Temperature $^{\circ}\text{C}$	Viscosity (kcps)
05M26-0R01012		0.01	1500	600°C	120~280
05M26-0R02012		0.02	1200		
05M26-0R03012		0.03	1200		
05M26-0R05012		0.05	1200		
05M26-0R10012		0.10	1200		
05M26-0R20012		0.20	1200		

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-25°C, with a shelf life of six months from the date of shipment.

Packaging Method :

1000g/can